



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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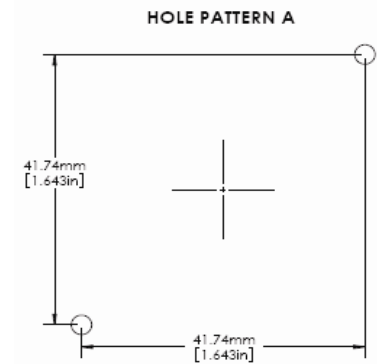
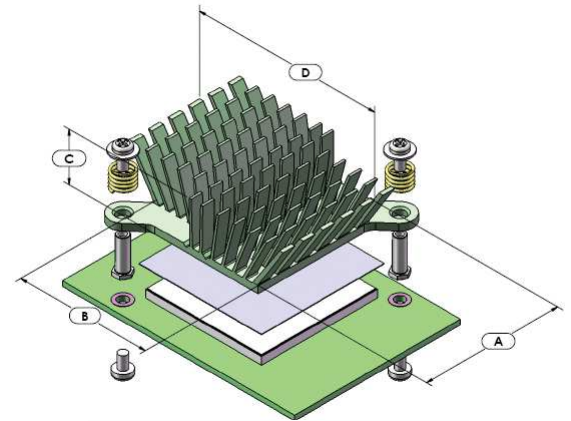
maxiFLOW™ Cross Cut High Performance Heat Sinks with Hardware Attachment



ATS PART # ATS-1040-C3-R0

Features & Benefits

- » For larger heat sinks and higher pre-loads, push pins with compression springs are an effective mounting choice. The push pin has a flexible barb at the end that is designed to engage with a pre-drilled hole in a PWB. The compression spring adds the necessary force to hold the assembly together. Provides better thermal performance than comparable size straight fin and pin fin heat sinks
- » Features proven high performance maxiFLOW™ heat sink spread fin array to maximize cooling surfaces
- » Ideal for tight spaced components where wider heat sinks can't be used
- » Provided with pre-assembled thermal interface material centered on base
- » PEM Standoff with compression and screws
- » Recommended through hole size in PCB is 3.00 mm



*Image above is for illustration purposes only.

Thermal Performance

| AIR VELOCITY | | THERMAL RESISTANCE (°C/W UNDUCTED) | |
|--------------|-----|------------------------------------|-------------------|
| FT/MIN | M/S | AIR FLOW STRAIGHT | AIR FLOW SIDEWAYS |
| 200 | 1.0 | 1.9 | 3.6 |
| 300 | 1.5 | 1.6 | 2.8 |
| 400 | 2.0 | 1.3 | 2.1 |
| 500 | 2.5 | 1.1 | 1.6 |
| 600 | 3.0 | 1 | 1.3 |

Product Details

| DIMENSION A | DIMENSION B | DIMENSION C | DIMENSION D | INTERFACE MATERIAL | FINISH |
|-------------|-------------|-------------|-------------|--------------------|----------------|
| 40 mm | 38 mm | 25 mm | 65 mm | CHOMERICS T-766 | GREEN ANODIZED |

NOTES:

- 1) DIMENSION C = HEAT SINK HEIGHT FROM BOTTOM OF THE BASE TO THE TOP OF THE FIN FIELD.
- 2) THERMAL PERFORMANCE DATA ARE PROVIDED FOR REFERENCE ONLY. ACTUAL PERFORMANCE MAY VARY BY APPLICATION.
- 3) ATS RESERVES THE RIGHT TO UPDATE OR CHANGE ITS PRODUCTS WITHOUT NOTICE
- 4) CONTACT ATS TO LEARN ABOUT CUSTOM OPTIONS AVAILABLE



ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).